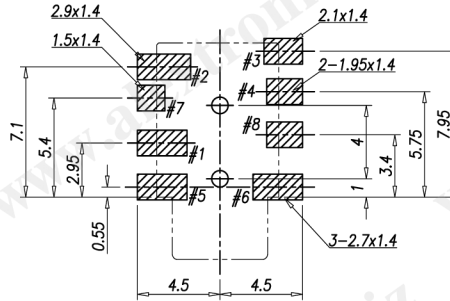
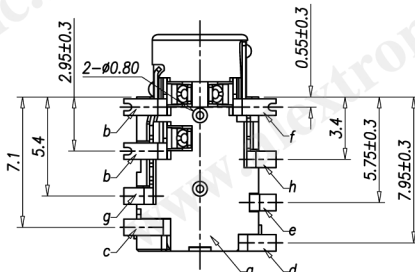
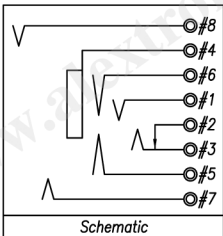
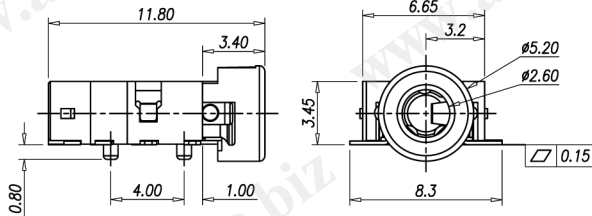


CATEGORY	DESCRIPTION	P/N #
CONNECTOR	2.5 Phone Jack, R/A, Without Metal Ring, SMT	AJ2370-30060-008M

REV.	ECN NO	DESCRIPTION	REVISED	DATE
A01		New Release	Luguan	2010.01.21

SPECIFICATION

1. Voltage Rating: DC 30V Min.
2. Current Rating: 1.0A Max.
3. Contact resistance: 30mΩ Max.
4. Insulation resistance: 100MΩ Min. (DC250V)
5. Operation Temperature: -25°C~70°C
6. Withstand Voltage: AC500V
7. Insertion force: 3kgf Max.
8. Extraction force: 0.3kgf Min.
9. life testing: 3,000 cycles
10. To conform with the "QC-03-045" & "RoHS DIRECTIVE"
11. Solder heat resistance: wave soldering 260°C 5 seconds



Recommend PCB Layout
(Jack Top View)
Tolerance: ±0.05mm

h	Terminal #8	1	Copper Alloy	Gold Flash Plating	
g	Terminal #7	1	Copper Alloy	Gold Flash Plating	
f	Terminal #6	1	Copper Alloy	Gold Flash Plating	
e	Terminal #4	1	Copper Alloy	Gold Flash Plating	
d	Terminal #3	1	Copper Alloy	Gold Flash Plating	
c	Terminal #2	1	Copper Alloy	Gold Flash Plating	
b	Terminal #1,5	2	Copper Alloy	Gold Flash Plating	
a	Housing	1	High Temperature Thermoplastic	Black	
NO.	PART NAME	QTY	MATERIAL	PLATING & COLOR	Remark

Product Drawing			
ALEXTRONIC			
UNLESS OTHERWISE SPECIFIED TOLERANCES	SCALE: 1/1	UNIT: mm	DWG.NO:
	SIZE: A3	PAGE: 1 OF 1	REV: A01
DECIMALS: X ±0.5 X.X ±0.3 X.XX ±0.2	ANGLES: X ±2' X.X ±1'	APPROVED BY XZQ	CHECKED BY PJ
		PREPARED BY Luguan	
CUSTOMER COPY			